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Kind regards,

Team Nexperia

CBT3245A-Q100

Octal bus switch

Rev. 1 — 20 March 2013 **Product data sheet**

1. General description

The CBT3245A-Q100 provides 8 bits of high-speed TTL-compatible bus switching. The low ON resistance of the switch allows connections to be made with minimal propagation delay.

The CBT3245A-Q100 is organized as one 8-bit bus switches with one output enable ($\overline{OE}$) input. When $\overline{OE}$ is LOW, the switch is on and port A is connected to the B port. When $\overline{OE}$ is HIGH, each switch is disabled.

This product has been qualified to the Automotive Electronics Council (AEC) standard Q100 (Grade 3) and is suitable for use in automotive applications.

2. Features and benefits

- Automotive product qualification in accordance with AEC-Q100 (Grade 3)
  - Specified from −40 °C to +85 °C
- 5 Ω switch connection between two ports
- TTL-compatible control input levels
- Multiple package options
- Latch-up protection exceeds 500 mA per JESD78
- ESD protection:
  - MIL-STD-883, method 3015 exceeds 2000 V
  - HBM JESD22-A114F exceeds 2000 V
  - MM JESD22-A115B exceeds 150 V (C = 200 pF, R = 0 Ω)

3. Ordering information

Table 1. Ordering information

Type number	Package			
	Temperature range	Name	Description	Version
CBT3245AD-Q100	−40 °C to +85 °C	SO20	plastic small outline package; 20 leads; body width 7.5 mm	SOT163-1
CBT3245APW-Q100	−40 °C to +85 °C	TSSOP20	plastic thin shrink small outline package; 20 leads; body width 4.4 mm	SOT360-1
CBT3245ABQ-Q100	−40 °C to +85 °C	DHVQFN20	plastic dual-in-line compatible thermal enhanced very thin quad flat package; no leads; 20 terminals; body 2.5 × 4.5 × 0.85 mm	SOT764-1

4. Functional diagram

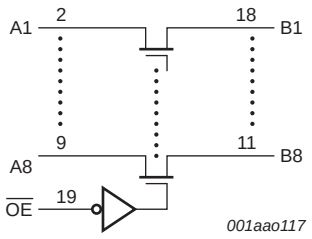


Fig 1. Logic diagram

5. Pinning information

5.1 Pinning

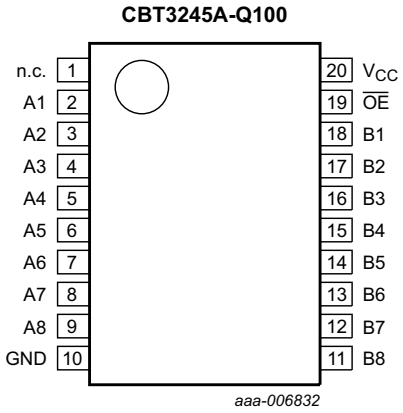
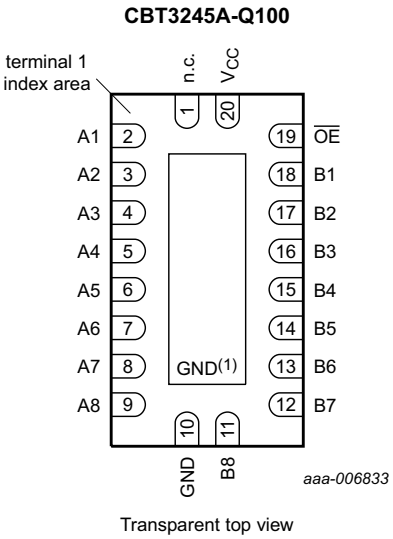


Fig 2. Pin configuration for SOT163-1 (SO20) and SOT360-1 (TSSOP20)



Transparent top view

(1) This is not a supply pin. The substrate is attached to this pad using conductive die attach material. There is no electrical or mechanical requirement to solder this pad. However, if it is soldered, the solder land should remain floating or be connected to GND.

Fig 3. Pin configuration for SOT764-1 (DHVQFN20)

5.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
n.c.	1	not connected
A1 to A8	2, 3, 4, 5, 6, 7, 8, 9	data input/output (A port)
GND	10	ground (0 V)
B1 to B8	18, 17, 16, 15, 14, 13, 12, 11	data input/output (B port)
$\overline{OE}$	19	output enable input (active LOW)
V_{CC}	20	positive supply voltage

6. Functional description

Table 3. Function selection[1]

Input	Input/output
$\overline{OE}$	**An, Bn**
L	An = Bn
H	Z

[1] H = HIGH voltage level; L = LOW voltage level; Z = high-impedance OFF-state.

7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).[1]
T_{amb} = −40 °C to +85 °C, unless otherwise specified.

Symbol	Parameter	Conditions		Min	Max	Unit
V_{CC}	supply voltage			−0.5	+7.0	V
V_I	input voltage		[2]	−0.5	+7.0	V
I_{OK}	output clamping current	V_O < 0 V		−50	-	mA
V_O	output voltage		[2]	−0.5	+7.0	V
I_O	output current	V_O < 0 V		-	±128	mA
I_{IK}	input clamping current	V_I = 0 V		−50	-	mA
T_{stg}	storage temperature			−65	+150	°C

[1] Stresses beyond the listed ones, may permanently damage the device. The ratings are stress ratings only and functional operation of the device at or beyond any conditions, other than those conditions indicated in Section 8., is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

[2] The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

8. Recommended operating conditions

Table 5. Operating conditions

All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{CC}	supply voltage		4.0	-	5.5	V
V_{IH}	HIGH-level input voltage		2.0	-	-	V
V_{IL}	LOW-level input voltage		-	-	0.8	V
T_{amb}	ambient temperature	operating in free air	−40	-	+85	°C

9. Static characteristics

Table 6. Static characteristics

Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions		T_{amb} = −40 °C to +85 °C			Unit
				Min	Typ[1]	Max	
V_{IK}	input clamping voltage	V_{CC} = 4.5 V; I_I = −18 mA		-	-	−1.2	V
I_I	input leakage current	V_{CC} = 5.5 V; V_I = GND or 5.5 V		-	-	±5	μA
I_{CC}	supply current	V_{CC} = 5.5 V; I_O = 0 mA; V_I = V_{CC} or GND		-	1	3	μA
ΔI_{CC}	additional supply current	per input pin; V_{CC} = 5.5 V; 1 input at 3.4 V, other inputs at V_{CC} or GND	[2]	-	-	3.5	mA
C_I	input capacitance	control pins; V_I = 3 V or 0 V		-	3.2	-	pF
$C_{io(off)}$	off-state input/output capacitance	port off; V_I = 3 V or 0 V; $\overline{OE}$ = V_{CC}		-	6.6	-	pF
R_{ON}	ON resistance	V_{CC} = 4.5 V; V_I = 0 V; I_I = 64 mA	[3]	-	5	7	Ω
		V_{CC} = 4.5 V; V_I = 0 V; I_I = 30 mA	[3]	-	5	7	Ω
		V_{CC} = 4.5 V; V_I = 2.4 V; I_I = −15 mA	[3]	-	10	15	Ω

[1] All typical values are at V_{CC} = 5 V, T_{amb} = 25 °C.

[2] This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

[3] Measured by the voltage drop between the An and the Bn terminals at the indicated current through the switch. The lowest voltage of the two (An or Bn) terminals, determines ON resistance.

10. Dynamic characteristics

Table 7. Dynamic characteristics

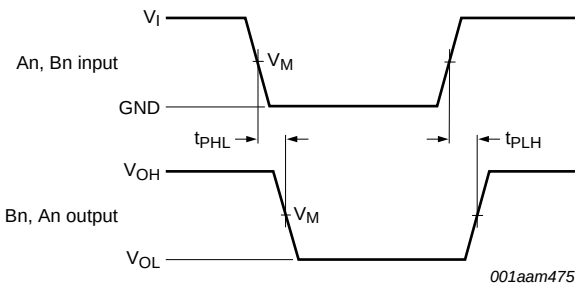
Voltages are referenced to GND (ground = 0 V). For test circuit see Figure 6.

Symbol	Parameter	Conditions		T_{amb} = −40 °C to +85 °C		Unit
				Min	Max	
t_{pd}	propagation delay	An, Bn to Bn, An; see Figure 4	[1][2]			
		V_{CC} = 5.0 V ± 0.5 V		-	0.25	ns
t_{en}	enable time	$\overline{OE}$ to An or Bn; see Figure 5	[2]			
		V_{CC} = 5.0 V ± 0.5 V		1.0	5.9	ns
t_{dis}	disable time	$\overline{OE}$ to An or Bn; see Figure 5	[2]			
		V_{CC} = 5.0 V ± 0.5 V		1.0	6.0	ns

[1] The propagation delay is the calculated RC time constant of the typical ON resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

[2] t_{pd} is the same as t_{PLH} and t_{PHL}.
t_{en} is the same as t_{PZL} and t_{PZH}.
t_{dis} is the same as t_{PLZ} and t_{PHZ}.

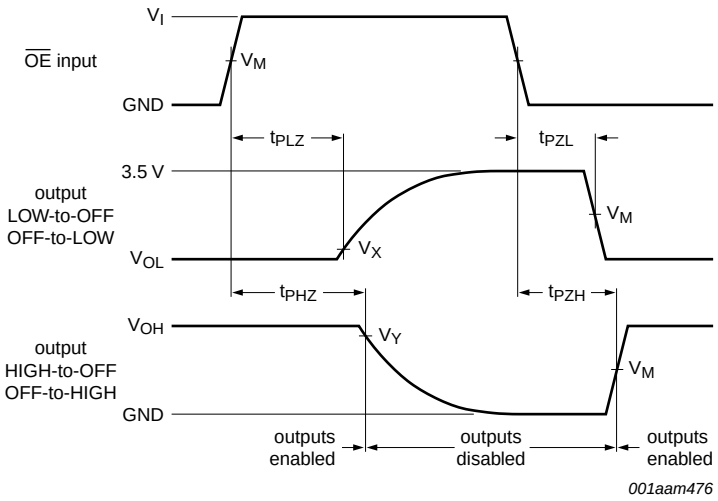
11. Waveforms



Measurement points are given in Table 8.

Logic levels: V_{OL} and V_{OH} are typical output voltage levels that occur with the output load.

Fig 4. The data input (An, Bn) to output (Bn, An) propagation delay times



Measurement points are given in Table 8.

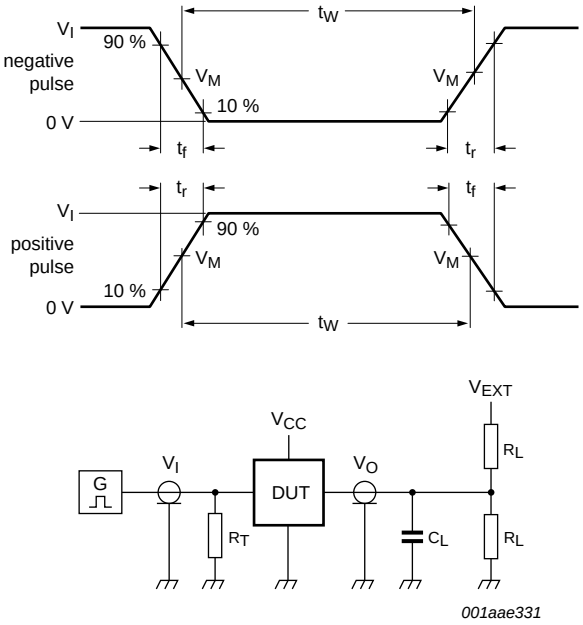
Logic levels: V_{OL} and V_{OH} are typical output voltage levels that occur with the output load.

Fig 5. Enable and disable times

Table 8. Measurement points

Supply voltage	Input		Output		
V_{CC}	V_I	V_M	V_M	V_X	V_Y
V_{CC} = 5.0 V ± 0.5 V	GND to 3.0 V	1.5 V	1.5 V	V_{OL} + 0.3 V	V_{OH} − 0.3 V

12. Test information



Test data is given in Table 9.

All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz; Z_o = 50 Ω.

The outputs are measured one at a time with one transition per measurement.

Definitions for test circuit:

R_L = Load resistance.

C_L = Load capacitance including jig and probe capacitance.

R_T = Termination resistance should be equal to output impedance Z_o of the pulse generator.

V_{EXT} = External voltage for measuring switching times.

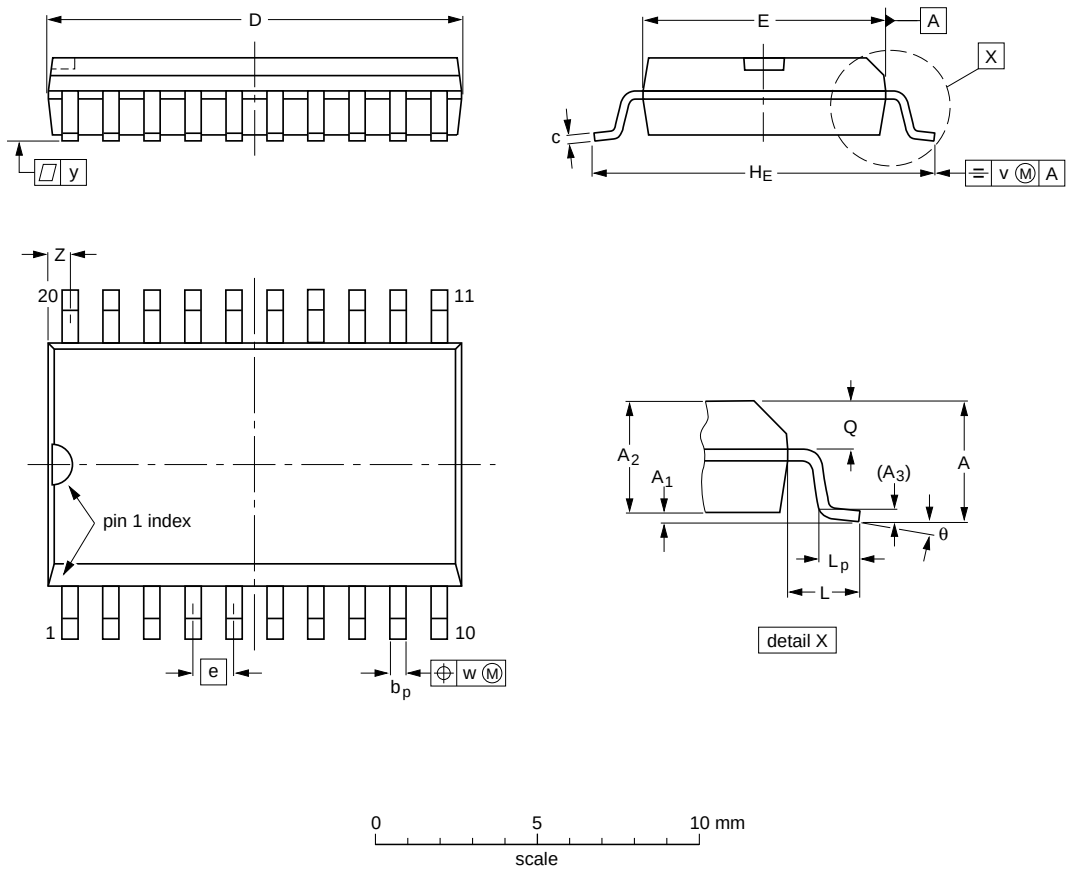
Fig 6. Test circuit for measuring switching times

Table 9. Test data

Supply voltage	Input		Load		V_{EXT}		
	V_I	t_r, t_f	C_L	R_L	t_{PLH}, t_{PHL}	t_{PLZ}, t_{PZL}	t_{PHZ}, t_{PZH}
V_{CC} = 5.0 V ± 0.5 V	GND to 3.0 V	≤ 2.5 ns	50 pF	500 Ω	open	7.0 V	open

13. Package outline

SO20: plastic small outline package; 20 leads; body width 7.5 mm **SOT163-1**



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	D (1)	E (1)	e	H_E	L	L_p	Q	v	w	y	Z (1)	θ
mm	2.65	0.3 0.1	2.45 2.25	0.25	0.49 0.36	0.32 0.23	13.0 12.6	7.6 7.4	1.27	10.65 10.00	1.4	1.1 0.4	1.1 1.0	0.25	0.25	0.1	0.9 0.4	8^o 0^o
inches	0.1	0.012 0.004	0.096 0.089	0.01	0.019 0.014	0.013 0.009	0.51 0.49	0.30 0.29	0.05	0.419 0.394	0.055	0.043 0.016	0.043 0.039	0.01	0.01	0.004	0.035 0.016	

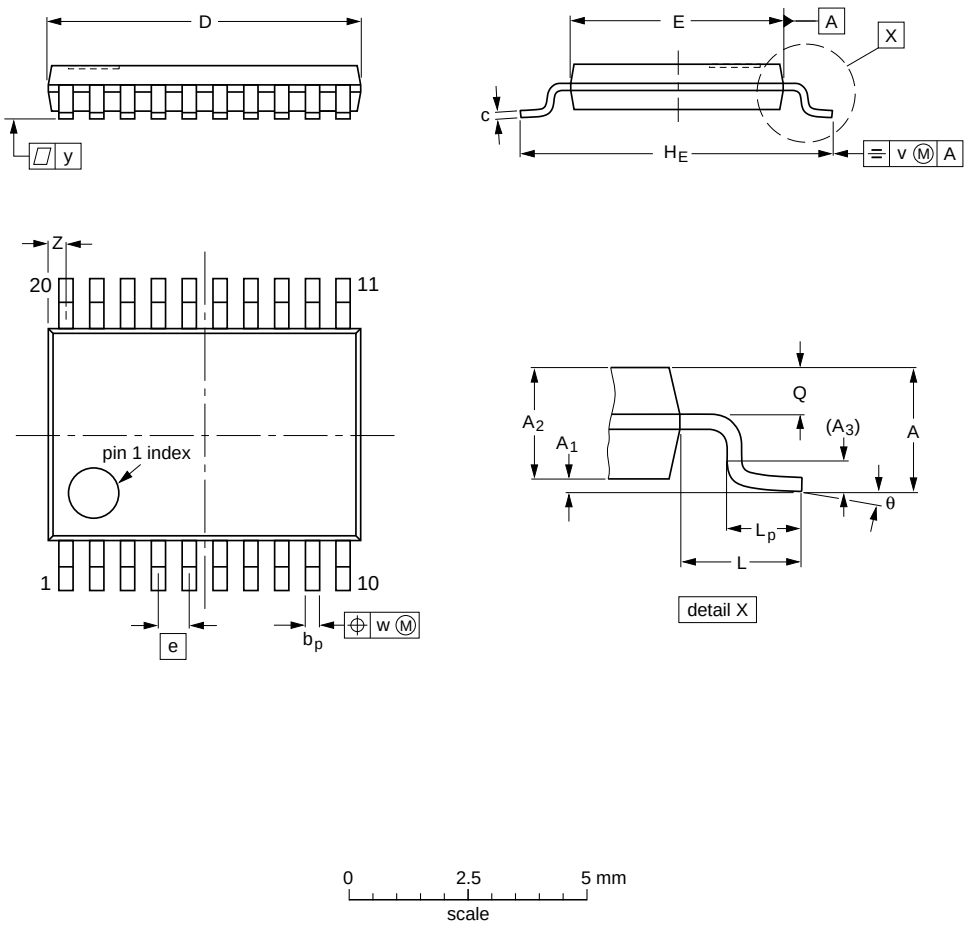
Note

1. Plastic or metal protrusions of 0.15 mm (0.006 inch) maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT163-1	075E04	MS-013				~~99-12-27~~ 03-02-19

Fig 7. Package outline SOT163-1 (SO20)

TSSOP20: plastic thin shrink small outline package; 20 leads; body width 4.4 mm **SOT360-1**



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	D (1)	E (2)	e	H_E	L	L_p	Q	v	w	y	Z (1)	θ
mm	1.1	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.2 0.1	6.6 6.4	4.5 4.3	0.65	6.6 6.2	1	0.75 0.50	0.4 0.3	0.2	0.13	0.1	0.5 0.2	8^o 0^o

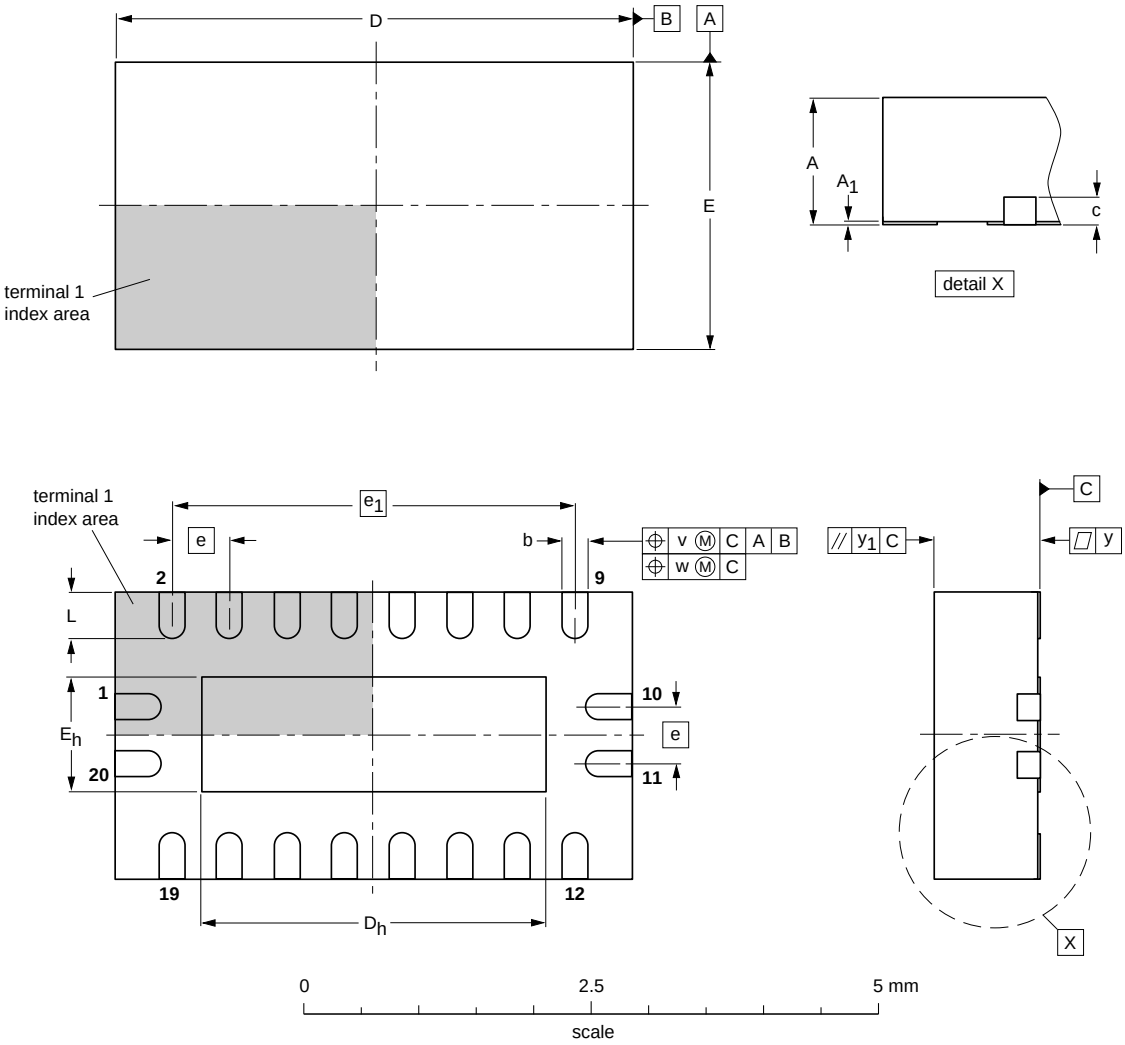
Notes

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT360-1		MO-153				~~99-12-27~~ 03-02-19

Fig 8. Package outline SOT360-1 (TSSOP20)

DHVQFN20: plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 20 terminals; body 2.5 x 4.5 x 0.85 mm **SOT764-1**



DIMENSIONS (mm are the original dimensions)

UNIT	$A^{(1)}$ max.	A_1	b	c	$D^{(1)}$	D_h	$E^{(1)}$	E_h	e	e_1	L	v	w	y	y_1
mm	1	0.05 0.00	0.30 0.18	0.2	4.6 4.4	3.15 2.85	2.6 2.4	1.15 0.85	0.5	3.5	0.5 0.3	0.1	0.05	0.05	0.1

Note

1. Plastic or metal protrusions of 0.075 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT764-1	- - -	MO-241	- - -			~~02-10-17~~ 03-01-27

Fig 9. Package outline SOT764-1 (DHVQFN20)

14. Abbreviations

Table 10. Abbreviations

Acronym	Description
CDM	Charged Device Model
ESD	ElectroStatic Discharge
DUT	Device Under Test
HBM	Human Body Model
MIL	Military
MM	Machine Model
PRR	Pulse Rate Repetition
TTL	Transistor-Transistor Logic

15. Revision history

Table 11. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
CBT3245A_Q100 v.1	20130320	Product data sheet	-	-

16. Legal information

16.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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18. Contents

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Document identifier: CBT3245A_Q100